

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number:

0739425200

Status:

Active

Overview:

[hdm](#)

Description:

2.00mm (.079") Pitch HDM® Board-to-Board Backplane Header, Vertical, Solder Tail, Open End, 144 Circuits

Documents:

[3D Model](#)

[Drawing \(PDF\)](#)

[RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

CSA

LR19980

UL

E29179

General

Product Family

Backplane Connectors

Series

[73942](#)

Application

Backplane

Comments

Solder Tail

Component Type

PCB Header

Overview

[hdm](#)

Product Name

HDM®

Style

N/A

Physical

Circuits (Loaded)

144

Circuits (maximum)

144

Color - Resin

Black, Natural

Durability (mating cycles max)

250

First Mate / Last Break

No

Flammability

94V-0

Guide to Mating Part

No

Keying to Mating Part

None

Material - Metal

Phosphor Bronze

Material - Plating Mating

Gold

Material - Plating Termination

Tin

Material - Resin

High Temperature Thermoplastic

Number of Columns

24

Number of Pairs

Open Pin Field

Number of Rows

6

Orientation

Vertical

PC Tail Length (in)

0.118 In

PC Tail Length (mm)

3.00 mm

PCB Retention

None

PCB Thickness Recommended (in)

0.098 In

PCB Thickness Recommended (mm)

2.50 mm

Packaging Type

Tube

Pitch - Mating Interface (in)

0.079 In

Pitch - Mating Interface (mm)

2.00 mm

Plating min: Mating (µin)

30

Plating min: Mating (µm)

0.75

Plating min: Termination (µin)

100

Plating min: Termination (µm)

2.5

Stackable

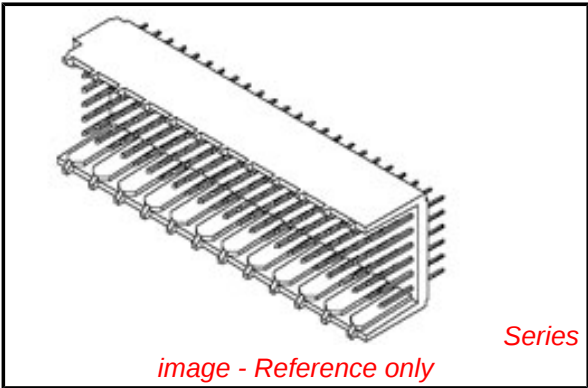
Yes

Surface Mount Compatible (SMC)

Yes

Temperature Range - Operating

-55°C to +105°C



EU RoHS

ELV and RoHS

Compliant

REACH SVHC

Contains SVHC: No

Halogen-Free

Status

Not Reviewed

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

[73942Series](#)

Mates With

[73632](#) HDM PLUS® Board-to-Board Daughtercard Receptacle. [73780](#) HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description	Product #
HDM® Backplane	0621001400
Insertion Signal	
Contact Tool	
Extraction Tool	0621001000

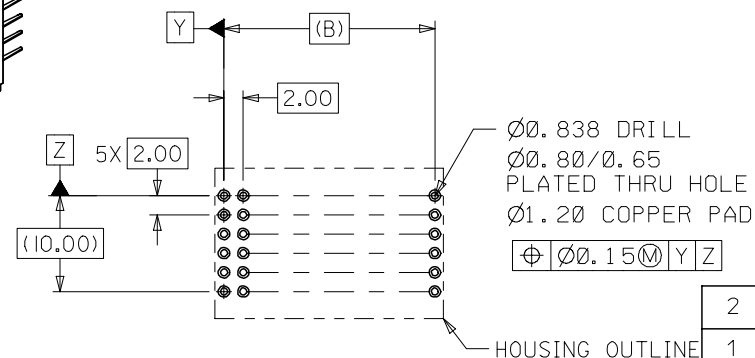
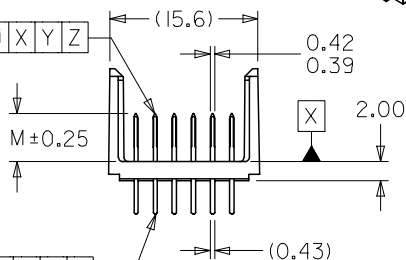
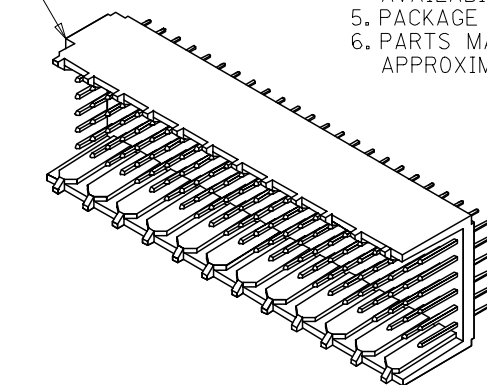
Termination Interface: Style	Through Hole
Electrical	
Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Voltage - Maximum	250V AC
Solder Process Data	
Duration at Max. Process Temperature (seconds)	40
Lead-free Process Capability	SMC & Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	3
Process Temperature max. C	260
Material Info	
Reference - Drawing Numbers	
Packaging Specification	PK-70873-0818
Sales Drawing	SD-73942-001

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1. MATERIALS: HOUSING--LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED,
UL94V-0, COLOR: BLACK,
TERMINAL: PHOSPHOR BRONZE.
2. FINISH: 0.75 MICROMETERS MINIMUM SELECTIVE GOLD (Au) IN MATING AREA;
2.50 MICROMETERS MINIMUM SELECTIVE TIN (Sn) IN TAIL AREA;
NICKEL (Ni) UNDERPLATE OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION
PS-73670-9999.
4. FOR MIXED CONTACT MATING LENGTHS, CONSULT FACTORY FOR
AVAILABILITY.
5. PACKAGE PER PK-70873-0818.
6. PARTS MARKED WITH PART NUMBER AND DATE CODE, ON EITHER SIDE,
APPROXIMATELY WHERE SHOWN.



PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN.

	2	A
E	1	G
	SHT	REV

- SEE NOTE 6

MODIFY FINISH NOTE EC NO: UCP2007-2259 DRAWN BY: IBARRA 2007/03/13 CHK'D BY: BARKER 2007/03/21 APPR: MILLER 2007/03/22	QUALITY SYMBOLS ▽=0 ▽=0	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
				mm	INCH	DRAWN BY JB INGHAM	DATE 1998/01/13	TITLE SALES ASSY HDM BACKPLANE OPEN END OPTION SOLDER TAIL VERSION MOLEX INCORPORATED			
			4 PLACES	± ---	± ---	CHECKED BY SREED	DATE 1998/01/13				
			3 PLACES	± ---	± ---	APPROVED BY CB IXLER	DATE 1998/01/13				
			2 PLACES	± 0.05	± ---	MATERIAL NO.	DOCUMENT NO.				
			1 PLACE	± 0.10	± ---	SEE CHART		SD-73942-001			
			ANGULAR ±1/2°								
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE B		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

MATERIAL NUMBER ASSIGNMENT

73942-* * 0 0

NUMBER	CIRCUIT SIZE	DIM "A"	DIM "B"	DIM "H"
0	72	23.84	22.00	2.0
1	144	47.84	46.00	2.0
2	72	23.84	22.00	2.5
3	144	47.84	46.00	2.5
4	72	23.84	22.00	3.0
5	144	47.84	46.00	3.0
6	72	23.84	22.00	3.5
7	144	47.84	46.00	3.5

NUMBER	DIM "M"
0	5.0
1	5.5
2	6.0

SEE SHEET 1 EC No. U81577 DRWN:JBINGHAM 98/02/03 CHK: SREED 98/02/03 APPR:CBIXLER 98/02/03 A	DESCRIPTION REV	QUALITY SYMBOLS MAJOR CRITICAL	GENERAL TOLERANCES: (UNLESS SPECIFIED)		SCALE --:--	DESIGN UNITS ☒ mm ☐ INCH	THIRD ANGLE PROJECTION	DIMENSIONS: ☐ mm ☐ INCH ☒ mm ONLY		SHT	REV
					DRAWN BY & DATE JBINGHAM 98/01/13			TITLE: SALES ASSY, HDM BACKPLANE OPEN END OPTION SOLDER TAIL VERSION		MATERIAL NO. DRAWING NO. SHEET NO.	2
					CHECKED BY & DATE SREED 98/01/13			APPROVED BY & DATE CBIXLER 98/01/13			
					APPROVED BY & DATE CBIXLER 98/01/13						
					CAD FILENAME S73942X2.DGN			SEE CHART			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.						SIZE B	